# **DATA SHEET**



# MOS FIELD EFFECT TRANSISTOR

2SK2487

# SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

#### **DESCRIPTION**

The 2SK2487 is N-Channel MOS Field Effect Transistor designed for high voltage switching applications.

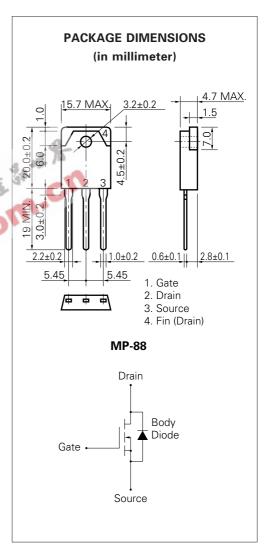
#### **FEATURES**

- Low On-Resistance RDS (on) = 1.6  $\Omega$  (VGS = 10 V, ID = 4.0 A)
- Low Ciss Ciss = 2 100 pF TYP.
- High Avalanche Capability Ratings

### ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Drain to Source Voltage	VDSS	900	V
Gate to Source Voltage	Vgss	±30	V
Drain Current (DC)	ID (DC)	±8.0	Α
Drain Current (pulse)*	ID (puls	e) ±20	Α
Total Power Dissipation (T <sub>c</sub> = 25 °C)	P <sub>T1</sub>	140	W
Total Power Dissipation (T <sub>A</sub> = 25 °C)	$P_{T2}$	3.0	W
Channel Temperature	$T_ch$	150	°C
Storage Temperature	$T_{\text{stg}}$	–55 to +150	°C
Single Avalanche Current**	las	8.0	Α
Single Avalanche Energy**	Eas	264	mJ

- \* PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1 %
- \*\* Starting Tch = 25 °C, Rg = 25  $\Omega$ , Vgs = 20 V  $\rightarrow$  0



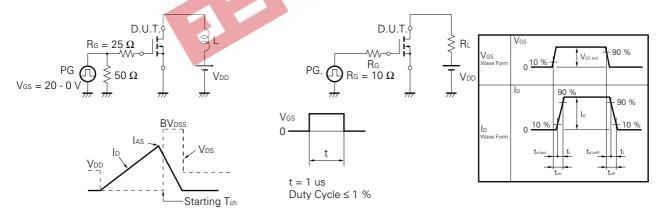


## **ELECTRICAL CHARACTERISTICS (TA = 25 °C)**

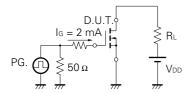
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-Resistance	RDS (on)		1.1	1.6	Ω	Vgs = 10 V, ID = 4.0 A
Gate to Source Cutoff Voltage	VGS (off)	2.5		3.5	V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA
Forward Transfer Admittance	yfs	3.0			S	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 4.0 A
Drain Leakage Current	IDSS			100	μΑ	V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0
Gate to Source Leakage Current	Igss			±100	nA	$V_{GS} = \pm 30 \text{ V, } V_{DS} = 0$
Input Capacitance	Ciss		2 100		pF	V <sub>DS</sub> = 10 V
Output Capacitance	Coss		310		pF	Vgs = 0
Reverse Transfer Capacitance	Crss		60		pF	f = 1 MHz
Turn-On Delay Time	td (on)		30		ns	ID = 4.0 A
Rise Time	tr		20		ns	Vgs = 10 V
Turn-Off Delay Time	td (off)		130		ns	V <sub>DD</sub> = 150 V
Fall Time	tf		23		ns	$R_G = 10 \Omega$
Total Gate Charge	Q <sub>G</sub>		65		nC	ID = 8.0 A
Gate to Source Charge	Qgs		11		nC	$V_{DD} = 450 \text{ V}$
Gate to Drain Charge	Q <sub>GD</sub>		29	2 13	nC	Vgs = 10 V
Body Diode Forward Voltage	VF (S-D)		1.0		V	IF = 8.0 A, VGS = 0
Reverse Recovery Time	trr		<b>7</b> 70	0	ns	IF = 8.0 A, VGS = 0
Reverse Recovery Charge	Qrr	1 .	5.0	1	μC	$di/dt = 50 A/\mu s$

## **Test Circuit 1 Avalanche Capability**

## **Test Circuit 2 Switching Time**

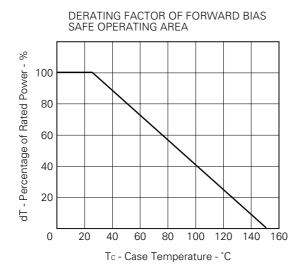


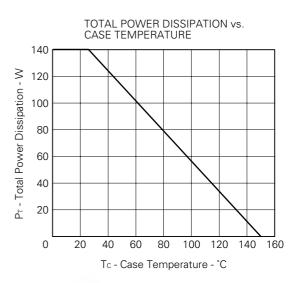
## **Test Circuit 3 Gate Charge**

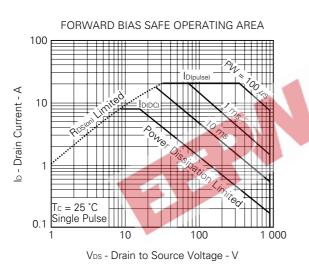


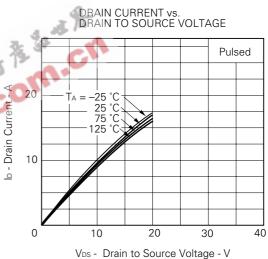
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

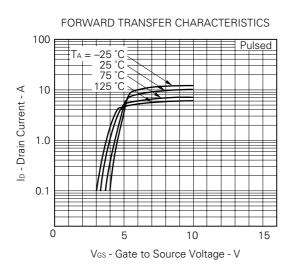
### TYPICAL CHARACTERISTICS (TA = 25 °C)



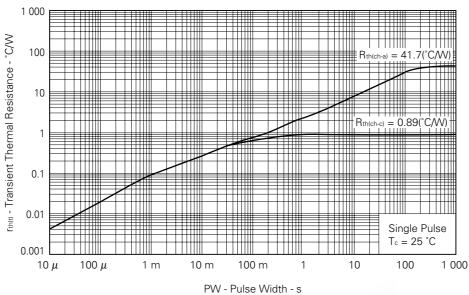


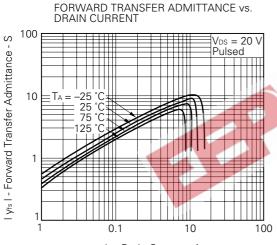


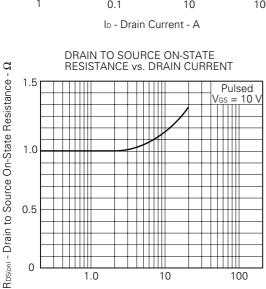




#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH







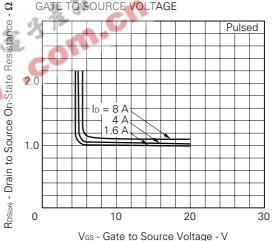
10

ID - Drain Current - A

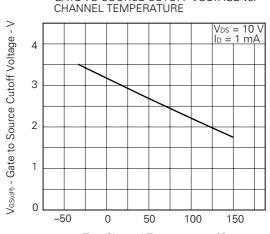
100

1.0

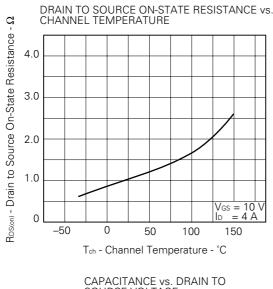
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE Pulsed

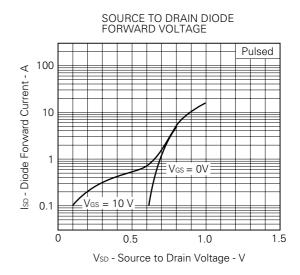


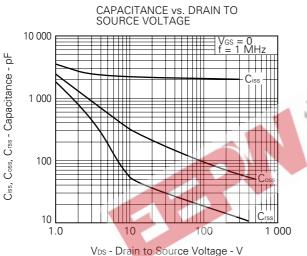
GATE TO SOURCE CUTOFF VOLTAGE vs.

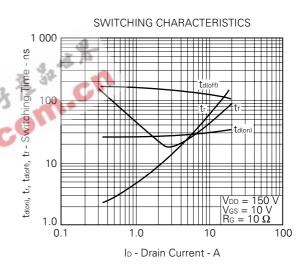


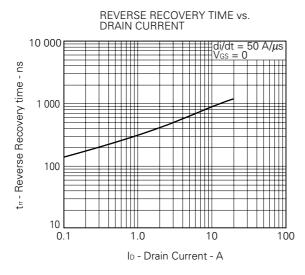
Tch - Channel Temperature - °C

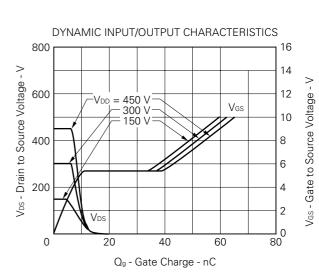


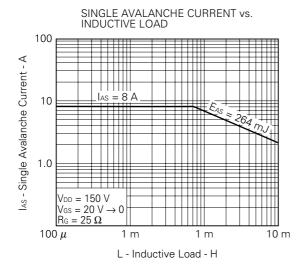


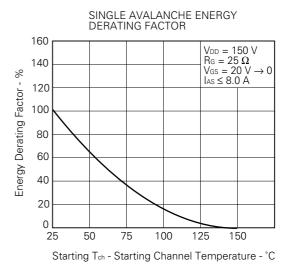
















#### **REFERENCE**

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037



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